CLAIM AMENDMENTS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A method, comprising:

directing an optical beam into a first end of an optical path having the first end and a second end disposed in a semiconductor substrate;

reflecting a first portion of the optical beam having a first center wavelength back out from the first end of the optical path by alternating a first silicon material and a second silicon material with first and second pluralities of silicon and polysilicon interfaces, respectively, disposed in the semiconductor substrate along the optical path between the first end and the second end; and

tuning the optical path to reflect a second portion of the optical beam having a second center wavelength back out from the first end of the optical path.

- 2. (Original) The method of claim 1 further comprising confining the optical beam to remain within the optical path between the first and second ends with an optical waveguide disposed in the semiconductor substrate between the first and second ends.
 - 3. (Cancelled)
- 4. (Currently Amended) The method of claim 1 wherein tuning the optical path comprises adjusting a temperature of the first and second pluralities of silicon and polysilicon interfaces first silicon material and the second silicon material with a heater disposed proximate to the optical path through the semiconductor substrate.

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5.-6. (Cancelled)

7. (Currently Amended) The method of claim 1 wherein alternating the first and

second pluralities of silicon and polysilicon interfaces first silicon material and the

second silicon material in the semiconductor substrate along the optical path form[[s]] a

Bragg grating.

8. - 29. (Cancelled)

30. (Previously Presented) A method, comprising:

directing an optical beam into a first end of an optical path having the first end

and a second end disposed in a semiconductor substrate;

reflecting a first portion of the optical beam having a first center wavelength back

out from the first end of the optical path by perturbing an effective index of refraction a

plurality of times along the optical path with a plurality of insulated conductor structures

protruding into the optical path; and

tuning the optical path to reflect a second portion of the optical beam having a

second center wavelength back out from the first end of the optical path.

31. (Previously Presented) The method of claim 30 wherein perturbing the

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effective index of refraction the plurality of times along the optical path comprises

applying a voltage to the plurality of insulated conductor structures to perturb a

concentration of free charge carriers a plurality of times along the optical path.

Attorney Docket No.: 42P11429 Application No.: 09/881,218 Examiner: Pritchett, Joshua L. Art Unit: 2872 32. (Previously Presented) The method of claim 30 wherein tuning the optical path comprises modulating charge in the optical path by modulating a voltage applied to

the insulated conductor structures.

33. (Previously Presented) The method of claim 30, further comprising

confining the optical beam to remain within the optical path between the first and second

ends with an optical waveguide disposed in the semiconductor substrate between the

first and second ends.

34. (Previously Presented) The method of claim 32 wherein confining the optical

beam with the optical waveguide comprises forming the optical waveguide with

dielectric layers of a silicon-on-insulator wafer.

35. (Previously Presented) The method of claim 30 wherein perturbing an

effective index of refraction a plurality of times along the optical path with a plurality of

insulated conductor structures protruding into the optical path forms a Bragg grating.

36. (Previously Presented) The method of claim 2 wherein confining the optical

beam to remain with in the waveguide comprises forming the optical waveguide with

dielectric layers of a silicon-on-insulator wafer.